

Data sheet Product FK 250 06 LF PAK

Board Level heatsinks>Heatsinks for D PAK and others

- direct PCB mounting thru solderable surface
available standard packing: loose parts (**bulk goods**) or reel (**TR** = tape and reel)
- **tape width:** 24 mm, **reel diameter:** 330 mm, **quantity:** FK 250 06 = 450, FK 250 08 = 450, FK 250 10 = 350

Features

for transistor:

- SOT 223
- Power SO 8
- D³ PAK (TO 268)
- Power_SO_20
- SO-14
- D² PAK (TO 263)
- Power SO 10
- D PAK (TO 252)
- SOT 669 LF PAK
- SO-16
- SO IC 8 FL MP
- SO-8
- Power SO 36

width:	15 mm
height:	6.5 mm
length:	8 mm
thermal resistance:	37 K/W
surface:	solderable surface
material:	copper (Cu)
material thickness:	0.6 mm

Technical Drawing



Data sheet Product FK 250 08 LF PAK

Board Level heatsinks>Heatsinks for D PAK and others

- direct PCB mounting thru solderable surface
available standard packing: loose parts (**bulk goods**) or reel (**TR** = tape and reel)
- **tape width:** 24 mm, **reel diameter:** 330 mm, **quantity:** FK 250 06 = 450, FK 250 08 = 450, FK 250 10 = 350

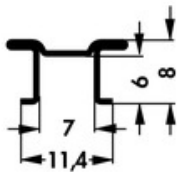
Features

for transistor:

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- Power SO 10
- D PAK (TO 252)
- SOT 669 LF PAK
- SO-16
- SO IC 8 FL MP
- SO-8
- Power SO 36

width:	15 mm
height:	8 mm
length:	8 mm
thermal resistance:	34.8 K/W
surface:	solderable surface
material:	copper (Cu)
material thickness:	0.6 mm

Technical Drawing



34,8 K/W

